Medium Voltage High Capacitance for General Use Specifications and Test Methods

No.	. Item		Specifications	Test Method		
1	Operating Temperature Range		-55 to +125°C	-		
2	Appearan	ice	No defects or abnormalities	Visual inspection		
3	Dimensio	ns	Within the specified dimensions	Using calipers and micrometers		
4	Dielectric Strength		No defects or abnormalities	No failure should be observed when 150% of the rated voltage (200% of the rated voltage in case of rated voltage: DC250V, 120% of the rated voltage in case of rated voltage: DC1kV) is applied between the terminations for 1 to 5 sec., provided the charge/discharge current is less than 50mA.		
5	Insulation Resistance (I.R.)		C≥0.01μF: More than 100MΩ • μF C<0.01μF: More than 10,000MΩ	The insulation resistance should be measured with DC500 \pm 50V (DC250 \pm 25V in case of rated voltage: DC250V) and within 60 \pm 5 sec. of charging.		
6	Capacitance		Within the specified tolerance	The considered D.F. should be considered to form		
7	Dissipation Factor (D.F.)		0.025 max.	The capacitance/D.F. should be measured at a frequency of 1±0.2kHz and a voltage of AC1±0.2V(r.m.s.)		
8	Capacitance Temperature Characteristics		Cap. Change Within ±15% (Temp. Range: –55 to +125°C)	The capacitance measurement should be made at each step specified in the Table. Step Temperature (°C) 1 25±2 2 Min. Operating Temp.±3 3 25±2 4 Max. Operating Temp.±2 5 25±2 • Pretreatment Perform a heat treatment at 150±00° C for 60±5 min. and then let sit for 24±2 hrs. at room condition.* Solder the capacitor to the testing jig (glass epoxy board) shown		
9	Adhesive Strength of Termination		No removal of the terminations or other defect should occur.	in Fig. 1. Then apply 10N force in the direction of the arrow. The soldering should be done using the reflow method and should be conducted with care so that the soldering is uniform and free of defects such as heat shock. 10N (5N : Size 1.6×0.8mm only), 10±1s Glass Epoxy Board Fig. 1		
	Vibration Resistance	Appearance	No defects or abnormalities	Solder the capacitor to the test jig (glass epoxy board).		
10		Capacitance	Within the specified tolerance	The capacitor should be subjected to a simple harmonic motion having a total amplitude of 1.5mm, the frequency being varied		
		D.F.	0.025 max.	uniformly between the approximate limits of 10 and 55Hz. The frequency range, from 10 to 55Hz and return to 10Hz, should be traversed in approximately 1 min. This motion should be applied for a period of 2 hrs. in each of 3 mutually perpendicular directions (total of 6 hrs.). Solder resist Glass Epoxy Board		

^{* &}quot;Room condition" Temperature: 15 to 35°C, Relative humidity: 45 to 75%, Atmospheric pressure: 86 to 106kPa

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No.	Ite	em	Specifications				Test Method			
	Deflection		No marking defects					Solder the capacitor to the testing jig (glass epoxy board) shown in Fig. 2.		
11			04.5 04.5 04.5 04.5 04.5 04.5					Then apply a force in the direction shown in Fig. 3. The soldering should be done using the reflow method and should be conducted with care so that the soldering is uniform and free of defects such as heat shock. 20 50 Pressurizing speed: 1.0mm/s Fig. 3.		
			1504		Fig. 2	· ()			R230	
			L×W (mm)	a	bimens	sion (mm)	d		Flexu	ire=1
			1.6×0.8	1.0	3.0	1.2			Capacitance meter	
			2.0×1.25	1.2 2.2	4.0	1.65	-		45 45	(in man)
			3.2×1.6 3.2×2.5	2.2	5.0 5.0	2.0	1.0		Fig. 3	(in mm)
			4.5×3.2	3.5	7.0	3.7			9	
			5.7×5.0	4.5	8.0	5.6				
12	Solderabi Terminati	•	75% of the terminations are to be soldered evenly and continuously.				d continuously.	Immerse the capacitor in a solution of ethanol (JIS-K-8101) and rosin (JIS-K-5902) (25% rosin in weight proportion). Immerse in solder solution for 2±0.5 sec. Immersing speed: 25±2.5mm/s Temp. of solder: 245±5°C Lead Free Solder (Sn-3.0Ag-0.5Cu) 235±5°C H60A or H63A Eutectic Solder		
	Resistance to Soldering Heat	Appearance	No marking defects					Preheat the capacitor at 120 to 150°C* for 1 min.		
		Capacitance Change	Within ±10% 0.025 max.					Immerse the capacitor in solder solution at 260±5°C for 10±1 sec. Let sit at room condition* for 24±2 hrs., then measure. •Immersing speed: 25±2.5mm/s •Pretreatment		
		D.F.								
13		I.R.	C≥0.01μF: More than 100MΩ • μF C<0.01μF: More than 10,000MΩ					Perform a heat treatment at 150± ₁ 8°C for 60±5 min. and then let sit for 24±2 hrs. at room condition.*		
					*Preheating for	or more than 3.2×2.5mm				
		Dielectric Strength	In accordance v	vith item N	0.4			Step 1 2	Temperature 100 to 120°C	Time 1 min.
		Annogranco	No marking defects						170 to 200°C	1 min.
		Appearance Capacitance Change	<u> </u>			Fix the capacitor to the supporting jig (glass epoxy board) showr in Fig. 4. Perform the 5 cycles according to the 4 heat treatments listed in				
		D.F.	0.025 max.					the following table. Let sit for 24±2 hrs. at room condition,* then measure.		
			C≧0.01µF: Mor	e than 100	MO • uF			Step	Temperature (°C)	Time (min.)
		I.R.	C<0.01μF: Mor					1	Min. Operating Temp.±3	30±3
								3	Room Temp. Max. Operating Temp.±2	2 to 3 30±3
	Tomporatura							4	Room Temp. ±2	2 to 3
14	Temperature Cycle	Dielectric						Pretreatment Perform a he		
		Strength	In accordance with item No.4				Cu Glass Epoxy Board Fig. 4	der resist		
15	Humidity (Steady State)	Appearance	No marking defects					Let the capacitor sit at 40±2°C and relative humidity of 90 to 95% for 500±2*dhrs.		
		Capacitance Change	Within ±15% 0.05 max. $C≥0.01μF: More than 10MΩ • μF C<0.01μF: More than 1,000MΩ$							
		D.F.				Remove and let sit for 24±2 hrs. at room condition,* then				
		I.R.				 neasure. Pretreatment Perform a heat treatment at 150[±]₁%°C for 60±5 min. and ther 				
		Dielectric Strength	In accordance v	vith item N	0.4			let sit for 24±	2 hrs. at room condition.*	

 $^{^{\}star}$ "Room condition" Temperature: 15 to 35°C, Relative humidity: 45 to 75%, Atmospheric pressure: 86 to 106kPa

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No.	Item		Specifications	Test Method		
	Life	Appearance	No marking defects	Apply 120% of the rated voltage (150% of the rated voltage in		
		Capacitance Change	Within ±15% (rated voltage: DC250V, DC630V) Within ±20% (rated voltage: DC1kV)	case of rated voltage: DC250V, 110% of the rated voltage in case of rated voltage: DC1kV) for 1,000±48hrs. at maximum		
16		D.F.	0.05 max.	operating temperature ±3°C. Remove and let sit for 24±2hrs. at room condition,* then measure.		
		I.R.	C≧0.01μF: More than 10MΩ • μF C<0.01μF: More than 1,000MΩ	The charge/discharge current is less than 50mA. •Pretreatment		
		Dielectric Strength	In accordance with item No.4	Apply test voltage for 60±5 min. at test temperature. Remove and let sit for 24±2 hrs. at room condition.*		
17	Humidity Loading (Application: DC250V, DC630V item)	Appearance	No marking defects	Apply the rated voltage at 40±2°C and relative humidity of 90 to 95% for 500±24hrs.		
		Capacitance Change	Within ±15%			
		D.F.	0.05 max.	Remove and let sit for 24±2 hrs. at room condition,* then measure.		
		I.R.	C≧0.01μF: More than 10MΩ • μF C<0.01μF: More than 1,000MΩ	Pretreatment Apply test voltage for 60±5 min. at test temperature.		
		Dielectric Strength	In accordance with item No.4	Remove and let sit for 24±2 hrs. at room condition.*		

^{* &}quot;Room condition" Temperature: 15 to 35°C, Relative humidity: 45 to 75%, Atmospheric pressure: 86 to 106kPa